

FIRE-RESISTANT ADHESIVE FILM AND FLAT CABLE USING THIS FILM

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Abstract of JP10149725

PROBLEM TO BE SOLVED: To provide the excellent adhesiveness and the excellent fire resistance by forming one surface of a board, which is made of thermoplastic polyester group resin, with an adhesive layer, which is formed of a thermoplastic polyolefin group resin and thermoplastic polyester, and forming this adhesive layer hard to burn. **SOLUTION:** As a thermoplastic polyolefin group resin having heat melting property to be used for an adhesive layer, polypropylene group resin is used. As a thermoplastic polyester group resin having heat melting property to be used for an adhesive layer, polyethylene terephthalate is used. The polyolefin group resin improves the water resistance of the adhesive layer, and the polyester group resin improves the adhesiveness thereof between a film board. As a halogen group fire-resistance agent, in relation to the forming temperature of the thermoplastic polyester group resin, which forms the board, the halogen group fire-resistant agent, of which decomposing temperature is 250 deg.C or more and of which halogen content is 20% or more, is desirable. In the case where content of the fire-resistant agent is small, fire-resistance is lowered, and in the case where the content thereof is large, adhesive strength is lowered.

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